



DATA SHEET

SEMICONDUCTOR

YSESDA0502CT3

BIDIRECTIONAL TVS DIODE ARRAY



APPLICATIONS

- ◆ Cell Phone Handsets and Accessories
- ◆ Microprocessor based equipment
- ◆ Personal Digital Assistants (PDA's)
- ◆ Notebooks, Desktops, and Servers
- ◆ Portable Instrumentation
- ◆ Peripherals
- ◆ Pagers

IEC COMPATIBILITY

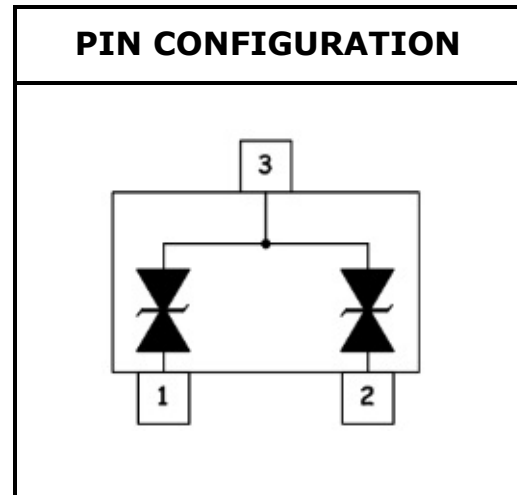
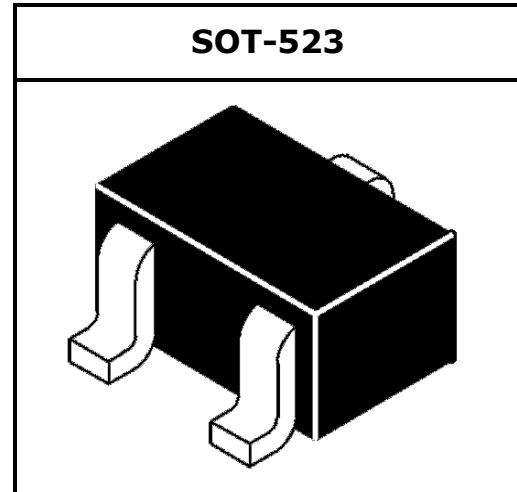
- ◆ IEC61000-4-2 (ESD) $\pm 30\text{kV}$ (air), $\pm 30\text{kV}$ (contact)
- ◆ IEC61000-4-4 (EFT) 40A (5/50 η s)

FEATURES

- ◆ 100 Watts Peak Pulse Power per Line ($t_p=8/20\mu\text{s}$)
- ◆ Protects one bidirectional I/O line
- ◆ Low clamping voltage
- ◆ Working voltages : 5.0V
- ◆ Low leakage current

MECHANICAL CHARACTERISTICS

- ◆ SOT-523 (1.6x1.6mm) Package
- ◆ Molding Compound Flammability Rating : UL 94V-0
- ◆ Weight 2.5 Milligrams (Approximate)
- ◆ Quantity Per Reel : 3,000pcs
- ◆ Reel Size : 7 inch
- ◆ Lead Finish : Lead Free



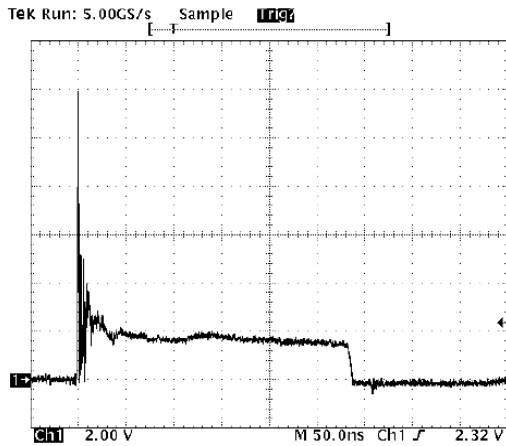
DEVICE CHARACTERISTICS

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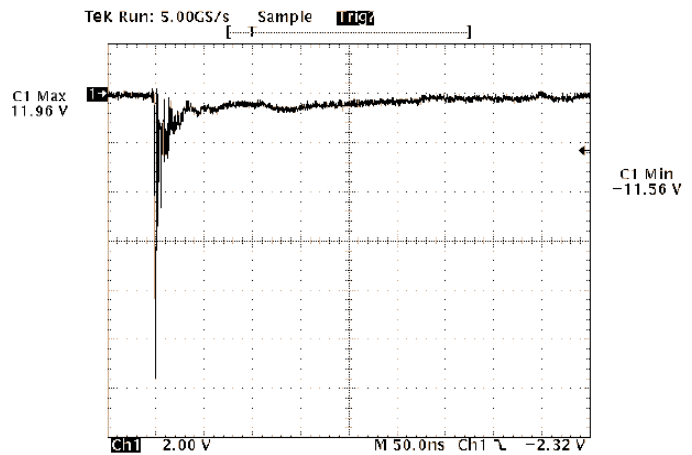
MAXIMUM RATINGS (@ 25°C Unless Otherwise Specified)			
PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power (tp=8/20µs waveform)	P _{PP}	100	Watts
Lead Soldering Temperature	T _L	260 (10 sec.)	°C
Operating Temperature Range	T _J	-55 ~ 150	°C
Storage Temperature Range	T _{STG}	-55 ~ 150	°C

ELECTRICAL CHARACTERISTICS PER LINE (@ 25°C Unless Otherwise Specified)									
PART NUMBER	DEVICE MARKING	V _{RWM}	V _B	I _T	V _C	V _C		I _R	C _T
		(V) (max.)	(V) (min.)	(mA)	@1A (max.)	(max.)	(@A)	(µA) (max.)	(pF) (typ.)
YSESDA0502CT3	5E	5	6	1	12	25	3	1	10

**ESD Clamping
(8kV Contact per IEC 61000-4-2)**

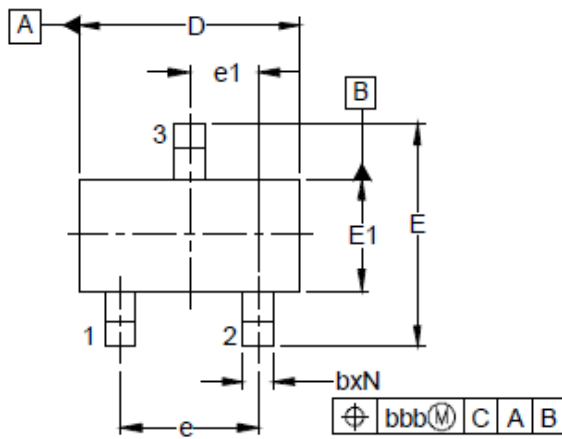


**ESD Clamping
(-8kV Contact per IEC 61000-4-2)**

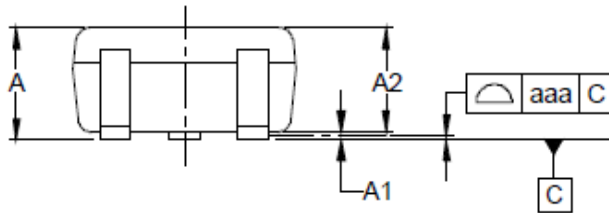


PACKAGE OUTLINE & DIMENSIONS

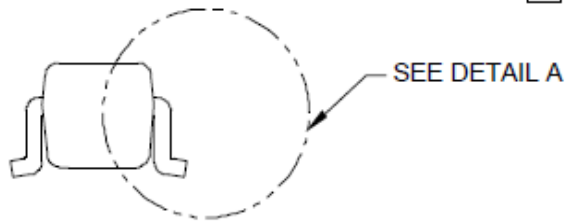
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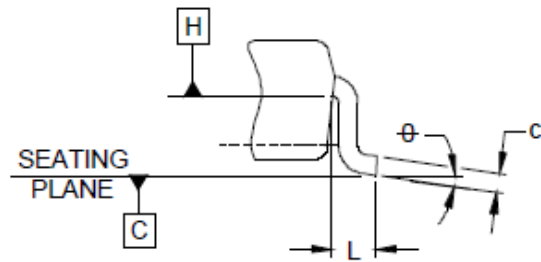
DIM	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX
A	.023	-	.035	0.60	-	0.90
A1	.000	-	.004	0.00	-	0.10
A2	.023	.030	.031	0.60	0.75	0.80
b	.005	-	.012	0.15	-	0.30
c	.003	-	.008	0.10	-	0.20
D	.059	.063	.067	1.50	1.60	1.70
E	.057	.063	.069	1.45	1.60	1.75
E1	.029	.031	.033	0.75	0.80	0.85
e	.039 BSC			1.00 BSC		
e1	.020 BSC			0.50 BSC		
L	(.009)			(0.22)		
N	3			3		
θ	0°	-	8°	0°	-	8°
aaa	.004			0.10		
bbb	.008			0.20		



SEATING PLANE



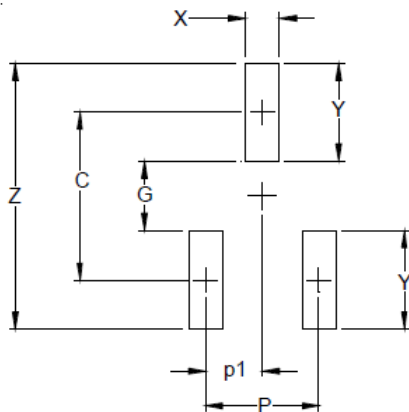
SIDE VIEW



SEATING PLANE

DETAIL A

* SOLDERING FOOTPRINT



DIM	DIMENSIONS	
	INCHES	MILLIMETERS
C	(.055)	(1.40)
P	.039	1.00
p1	.020	0.50
G	.024	0.60
X	.016	0.40
Y	.031	0.80
Z	.087	2.20